

Customer Information Notification	2016060251							
Issue Date: 26-Jul-2016 Effective Date: 24-Oct-2016	×							
Dear Product Change Notices Newark,								
Here's your personalized quality information concerning products Newark purchased from NXP. For detailed information we invite you to view this notification online								
Management Summary Miner change of corrier tand decire for products in SOD222 posters.								
Minor change of carrier tape design for products in SOD323 package.								
[] Wafer Fab [] Assembly [] Mechanical Specificate Materials Materials [] Wafer Fab [] Assembly [X]Packing/Shipping/Lab								
Location Location ng	Equipment coverage							

Introduction of optimized carrier tape for products in SOD323 package

Information Notification

Minor change of carrier tape design for products in SOD323 package.

The design of the area between the pockets of the carrier tape will be changed to optimize the flatness of cover tape along the carrier tape.

There will be no change to any specification or dimensional measures of the carrier tape and the cover tape including no change of peel off force of the cover tape (an illustration of the change is enclosed herewith).

Why do we issue this Information Notification

By modifying the cross bar between the pockets we can ensure a better balanced distance between the components and the cover tape.

This minor modification does not impact the specification of the carrier tape nor the peel off force/behavior of the cover tape.

Identification of Affected Products

Product identification does not change

Impact

no impact to the product's functionality anticipated.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Affected products and sales history information: see attached file

Additional documents: view online

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please <u>contact NXP "Global Quality Support Team"</u>.

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Wali Ahmad

Position Senior Quality Engineer & Customer Support

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Customer Focus, Passion to Win.

NXP Quality Management Team.

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Changed Orderable Part#	Changed Part 12NC	Changed Part Number	Changed Part Description	Package Outline	Package Name	Product Line
BAP63-03,115	934056542115	BAP63-03	PIN DIODE	SOD323	SODZ	BL Smart Antenna
BAP70-03,115	934056620115	BAP70-03	PIN DIODE	SOD323	SOD2	BL Smart Antenna